

COOLING SYSTEM AND METHOD FOR SEMICONDUCTOR
RELIABILITY, FUNCTIONALITIES AND BURN-IN TEST

ABSTRACT

[0054] The present invention provides a modular cooling system for a reliability, functionality and burn-in test equipment having a plurality of device under test (DUT). The modular cooling system is adapted for cooling each tray of the test equipment, thus, the modular cooling system is relatively small. The modular cooling system further provides a multiple-tiers compartment cooling head adapted to absorb heat from the DUT.

[0055] FIG. 1 for publication.